# EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 1 | ("6660560").PN. | USPAT; USOCR | OR | OFF | 2006/08/08 13:06 |
| L2 | 1155 | (@ad<"20010105") and (chip or die) and (no adj flow) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:28 |
| L3 | 7 | L2 and (underfill with (silica or filler or particle$1 or sio or alo or aln or (aluminum adj (oxide or nitride)) or (silicon adj dioxide) or (silicon adj nitride))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:20 |
| L4 | 38 | L2 and ((underfill or encapsulant or adhesive or encpasulation) with (silica or filler or particle$1 or sio or alo or aln or (aluminum adj (oxide or nitride)) or (silicon adj dioxide) or (silicon adj nitride))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:23 |
| L5 | 31 | L4 not L3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:21 |
| L6 | 525 | (@ad<"20010105") and 438/108. ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:46 |
| L7 | 74 | L6 and ((underfill or encapsulant or adhesive or encpasulation) with (silica or filler or particle$1 or sio or alo or aln or (aluminum adj (oxide or nitride)) or (silicon adj dioxide) or (silicon adj nitride))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:24 |
| L8 | 72 | L7 not l3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:23 |

| L9 | 72 | L8 not L5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:23 |
|---|---|---|---|---|---|---|
| L10 | 29 | L6 and ((underfill or encapsulant or adhesive or encpasulation) with (silica or sio or alo or aln or (aluminum adj (oxide or nitride)) or (silicon adj dioxide) or (silicon adj nitride))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:29 |
| L11 | 22 | L10 and (filler or particle$1) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:25 |
| L12 | 1611 | (@ad<"20010105") and (chip or die) and underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:28 |
| L13 | 31 | L12 and ((bump or terminal or contact or eletrode or pad) with (silica or sio or alo or aln or (aluminum adj (oxide or nitride)) or (silicon adj dioxide) or (silicon adj nitride))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:45 |
| L14 | 87 | 257/777,778.ccls. and ((bump or terminal or contact or eletrode or pad) with (silica or sio or alo or aln or (aluminum adj (oxide or nitride)) or (silicon adj dioxide) or (silicon adj nitride))) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:45 |
| L15 | 47 | L14 and (@ad<"20010105") | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/08/08 13:46 |